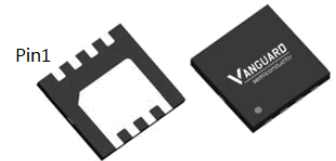


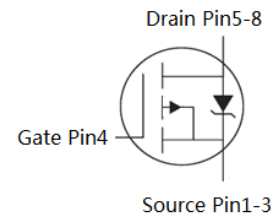
## Features

- P-Channel, -2.5V Logic Level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=-4.5V$
- 100 Avalanche Tested
- Fast Switching
- Pb-free lead plating; RoHS compliant

$V_{DS}$	-12	V
$R_{DS(on),TYP} @ V_{GS}=-4.5V$	4.8	m $\Omega$
$R_{DS(on),TYP} @ V_{GS}=-2.5V$	6	m $\Omega$
$I_D$	-65	A


**TDFN3.3x3.3**


Part ID	Package Type	Marking	Tape and reel information
VSB004P02KS	TDFN3.3x3.3	004P02K	5000pcs/reel



### Maximum ratings, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-12	V
$I_S$	Diode continuous forward current	$T_A = 25^\circ\text{C}$ -65	A
$I_D$	Continuous drain current @ $V_{GS} = -4.5V$	$T_A = 25^\circ\text{C}$ -65	A
		$T_A = 100^\circ\text{C}$ -42	A
$I_{DM}$	Pulse drain current tested ①	$T_A = 25^\circ\text{C}$ -260	A
EAS	Avalanche energy, single pulsed ②	12	mJ
$P_D$	Maximum power dissipation	$T_A = 25^\circ\text{C}$ 42	W
$V_{GS}$	Gate-Source voltage	$\pm 8$	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	$^\circ\text{C}$
<b>Thermal Characteristics</b>			
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.0	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	35	$^\circ\text{C/W}$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-12	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(Tc=25°C)	V <sub>DS</sub> =-9.6V, V <sub>GS</sub> =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V <sub>DS</sub> =-9.6V, V <sub>GS</sub> =0V	--	--	-100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	--	-1	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A	--	4.8	6	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-16A	--	6	8	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-6V, V <sub>GS</sub> =0V, f=1MHz	--	6580	--	pF
C <sub>oss</sub>	Output Capacitance		--	2065	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	2060	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz		42		Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-6V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-4.5V	--	73	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	15	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	16	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-6V, I <sub>D</sub> =-20A, R <sub>G</sub> =6Ω, V <sub>GS</sub> =-4.5V	--	26	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	38	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	195	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	89	--	nS
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =-20A, V <sub>GS</sub> =0V	--	-0.8	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>sd</sub> =-20A, V <sub>GS</sub> =0V	--	38	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		di/dt=-100A/μs		20	

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = -7A, V<sub>GS</sub> = -5V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.



### Typical Characteristics

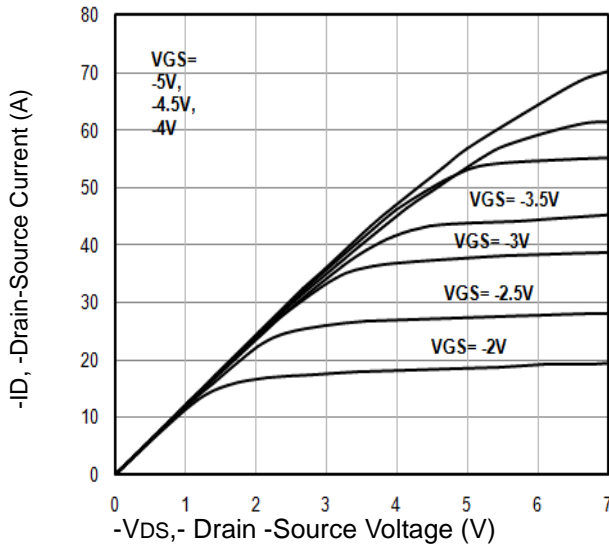


Fig1. Typical Output Characteristics

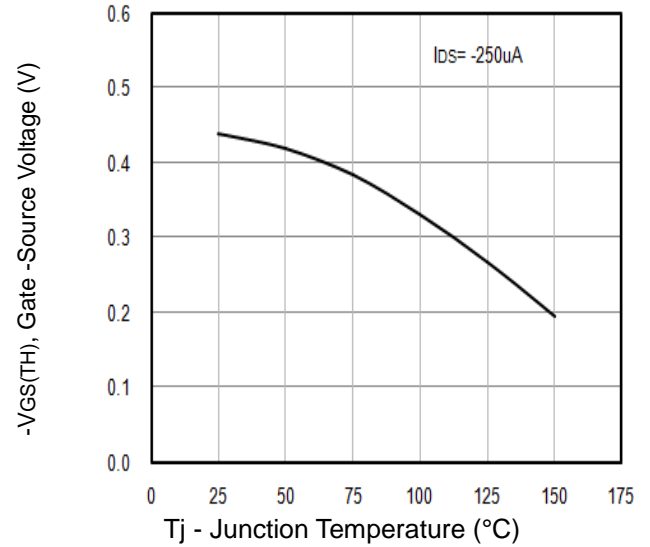


Fig2. Threshold Voltage Vs. Temperature

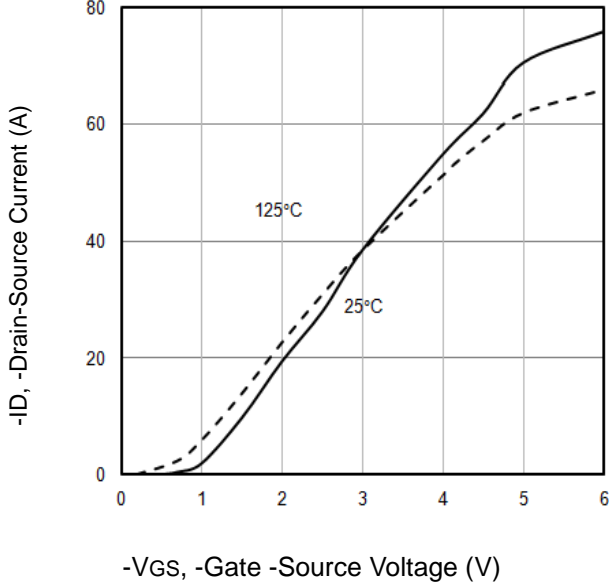


Fig3. Typical Transfer Characteristics

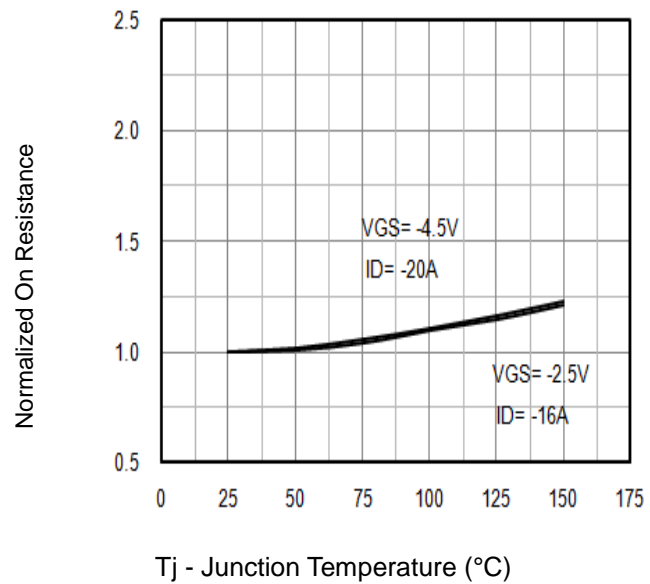


Fig4. Normalized On-Resistance Vs. Temperature

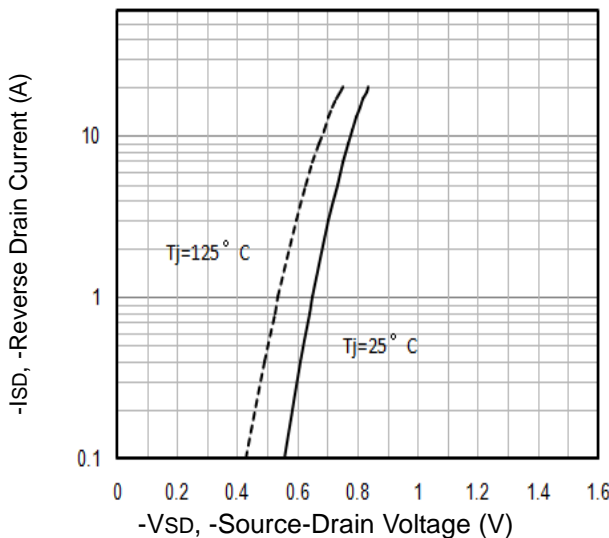


Fig5. Typical Source-Drain Diode Forward Voltage

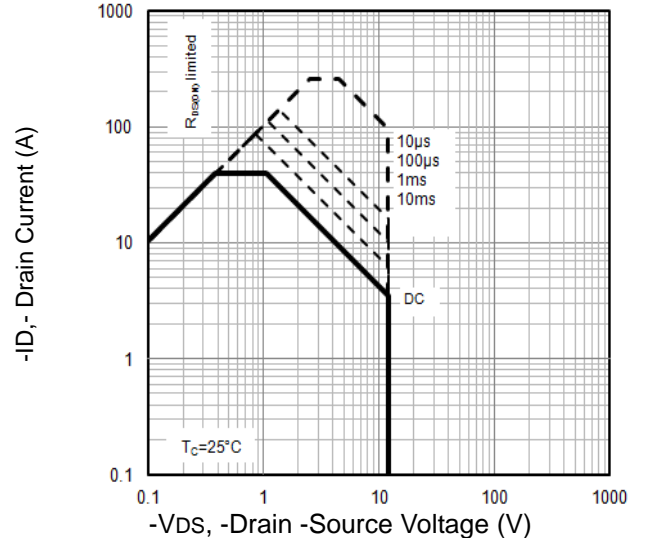


Fig6. Maximum Safe Operating Area

Typical Characteristics

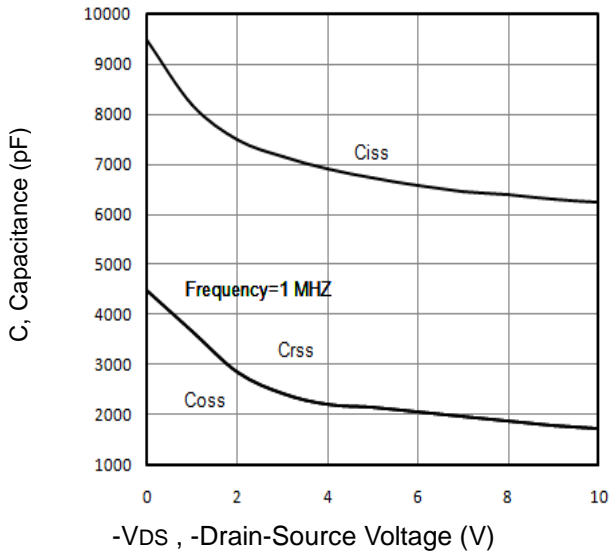


Fig7. Typical Capacitance Vs.Drain-Source Voltage

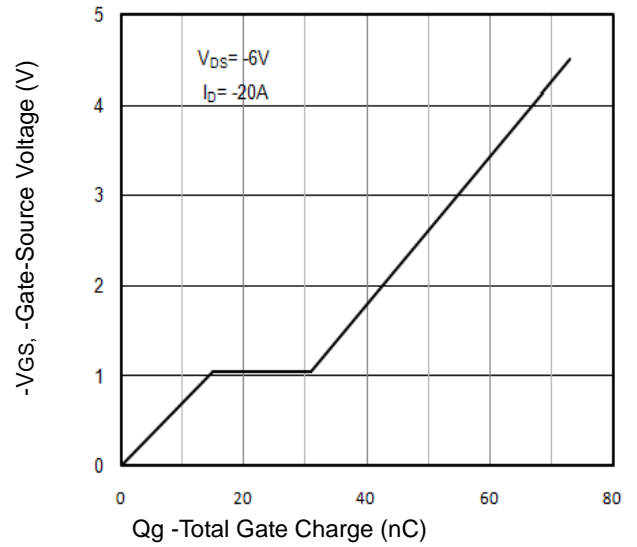


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

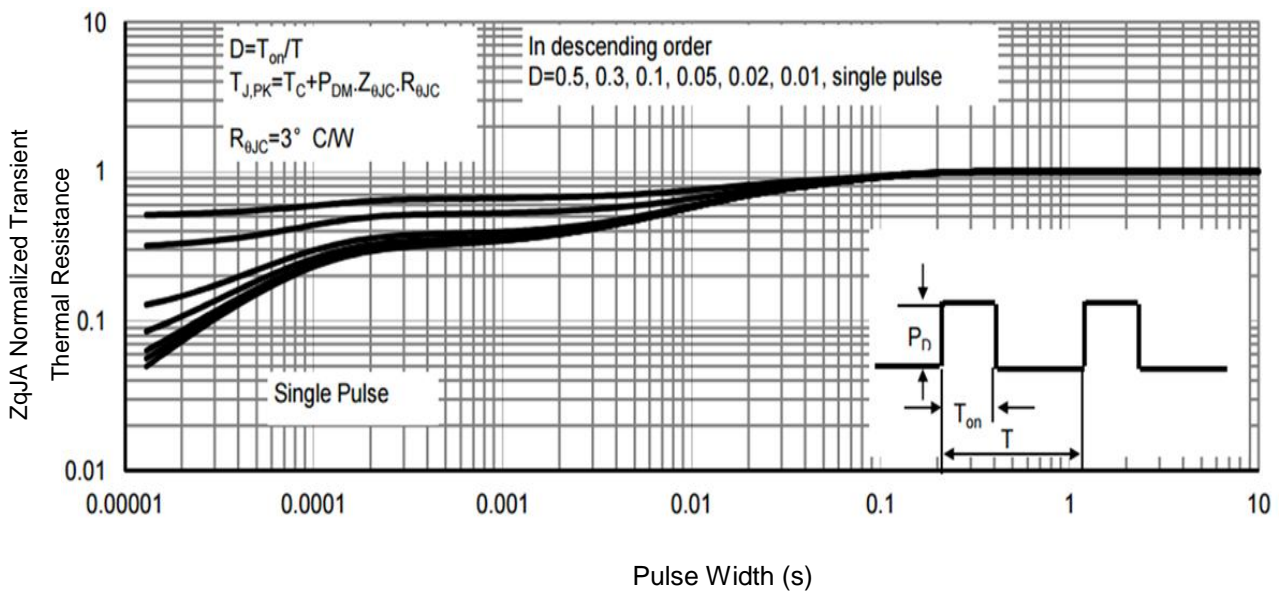


Figure 9: Normalized Maximum Transient Thermal

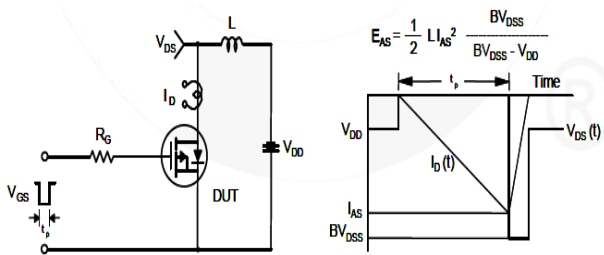


Fig10. Unclamped Inductive Test Circuit and Waveforms

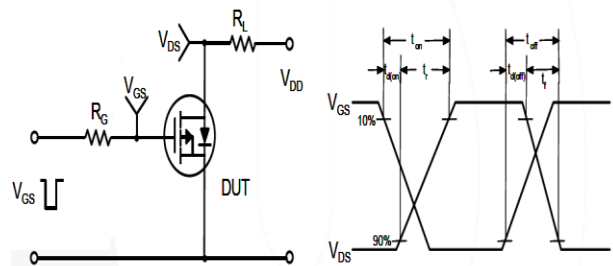
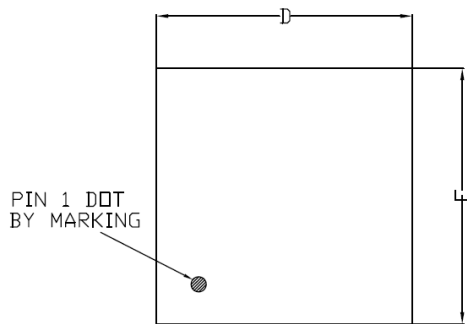
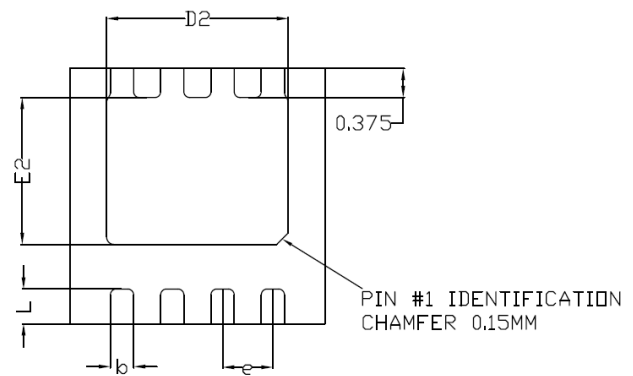


Fig11. Switching Time Test Circuit and waveforms

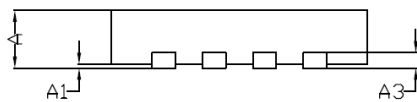
TDFN3.3x3.3 Package Outline Data



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Lead finish : NiPdAu

**DIMENSIONS** ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	A1	0.00	--	0.05
A3	0.20 REF			D	3.25	3.30	3.35
E	3.25	3.30	3.35	D2	2.30	2.35	2.40
E2	1.85	1.90	1.95	b	0.25	0.30	0.35
L	0.35	0.45	0.55	e	0.65 BSC		

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